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Appln. No. 10/532,949
Response dated June 19, 2008 to
Reply to Office Action of March 28, 2008

Amendments to the Specification:

Please amend the Abstract of the Disclosure as follows. A clean copy of the Abstract is enclosed.

ABSTRACT

A jig for holding and conveyance ~~having~~ includes a plate having a weak-adherence adhesive pattern on a ~~[[plate]]~~ surface ~~on which~~ and a printed circuit board having a conductive portion and a non-conductive portion on the surface of an insulating substrate ~~is placed and held~~. The weak-adherence adhesive pattern is formed ~~by being restricted to~~ at a position corresponding to the non-conductive portion. ~~A jig for holding and conveyance is also disclosed which has a fluorine-based resin layer on a plate surface on which a printed circuit board having a conductive pattern on the surface of an insulating substrate is placed and held. On the fluorine-based resin layer, the printed circuit board is held so that the conductor pattern surface of the printed circuit board is approximately parallel to the plate surface. A jig for holding and conveyance can be provided which is capable of reducing manufacturing defects in a step of connecting electronic components or the like on the surface of a thin printed circuit board or in a step of manufacturing the printed circuit board, and which is capable of low cost production.~~ Alternatively, the weak-adherence adhesive

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pattern subjected to surface roughening is formed on a surface of
the weak-adhesive layer at a position corresponding to the
conductive portion.